



YEA SHIN TECHNOLOGY CO., LTD

YS6906ZBB

## N-Channel Enhancement MOSFET

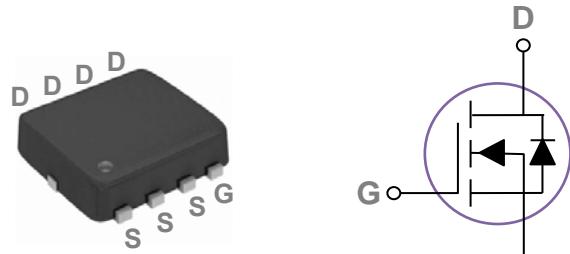
**VDS= 60V, ID= 33A**



### Features

- 60V, 33A,  $R_{DS(ON)} = 21m\Omega$  @  $V_{GS} = 10V$
- Improved  $dv/dt$  capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### PPAK3x3 Pin Configuration



### Applications

- Motor Drive
- Power Tools
- LED Lighting

### Absolute Maximum Rating $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ C$ )	33	A
	Drain Current – Continuous ( $T_c=100^\circ C$ )	20	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	132	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	42	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	29	A
$P_D$	Power Dissipation ( $T_c=25^\circ C$ )	44.6	W
	Power Dissipation – Derate above $25^\circ C$	0.36	W/ $^\circ C$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	$^\circ C / W$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	2.8	$^\circ C / W$

# DEVICE CHARACTERISTICS

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Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

### Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=250\mu\text{A}$	60	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_{\text{D}}=1\text{mA}$	---	0.07	---	$\text{V}/^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=60\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=48\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	10	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	$\text{nA}$

### On Characteristics

$R_{\text{DS(ON)}}$	Static Drain-source On-Resistance <sup>3</sup>	$V_{\text{GS}}=10\text{V}$ , $I_{\text{D}}=15\text{A}$	---	17	21	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_{\text{D}}=8\text{A}$	---	20	24	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_{\text{D}}=250\mu\text{A}$	1.2	1.8	2.2	V
			---	-5	---	$\text{mV}/^\circ\text{C}$
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}$ , $I_{\text{D}}=10\text{A}$	---	9	---	S

### Dynamic and Switching Characteristics

$Q_g$	Total Gate Charge <sup>3,4</sup>	$V_{\text{DS}}=30\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_{\text{D}}=15\text{A}$	---	28	42	nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>3,4</sup>		---	3.5	7	
$Q_{\text{gd}}$	Gate-Drain Charge <sup>3,4</sup>		---	6.5	10	
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>3,4</sup>	$V_{\text{DD}}=30\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_{\text{G}}=6\Omega$ , $I_{\text{D}}=1\text{A}$	---	7.2	14	ns
$T_r$	Rise Time <sup>3,4</sup>		---	38	72	
$T_{\text{d(off)}}$	Turn-On Delay Time <sup>3,4</sup>		---	34	65	
$T_f$	Fall Time <sup>3,4</sup>		---	8.2	16	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=20\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	1110	1665	pF
$C_{\text{oss}}$	Output Capacitance		---	110	165	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	60	90	
$R_g$	Gate Resistance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=0\text{V}$ , $f=1\text{MHz}$	---	2.2	4.4	$\Omega$

### Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	33	A
$I_{\text{SM}}$	Pulsed Source Current <sup>3</sup>		---	---	66	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>3</sup>	$V_{\text{GS}}=0\text{V}$ , $I_{\text{s}}=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V
$t_{\text{rr}}$	Reverse Recovery Time	$V_{\text{GS}}=0\text{V}$ , $I_{\text{s}}=-1\text{A}$ , $di/dt=100\text{A}/\mu\text{s}$ $T_J=25^\circ\text{C}$	---	19.6	---	ns
$Q_{\text{rr}}$	Reverse Recovery Charge		---	14.2	---	nC

Note :

- Repetitive Rating : Pulsed width limited by maximum junction temperature.
- $V_{\text{DD}}=25\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}=29\text{A}$ ,  $R_{\text{G}}=25\Omega$ , Starting  $T_J=25^\circ\text{C}$ .
- The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$ .
- Essentially independent of operating temperature.

# DEVICE CHARACTERISTICS

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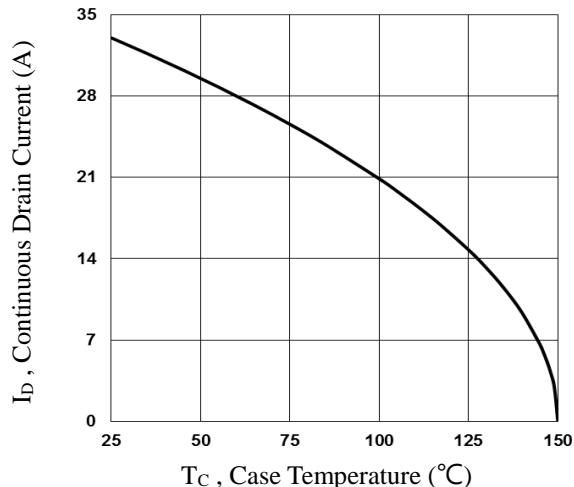


Fig.1 Continuous Drain Current vs.  $T_C$

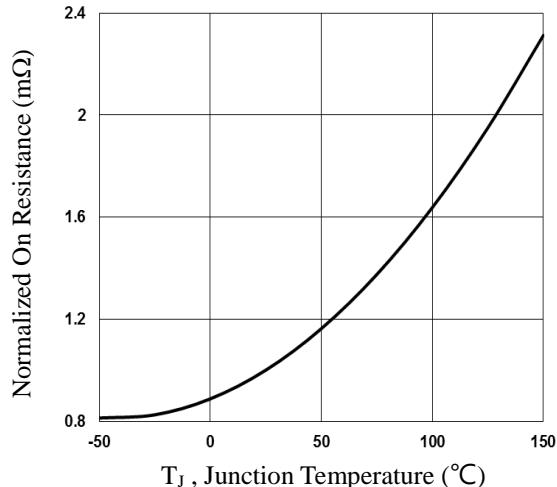


Fig.2 Normalized RDS(on) vs.  $T_J$

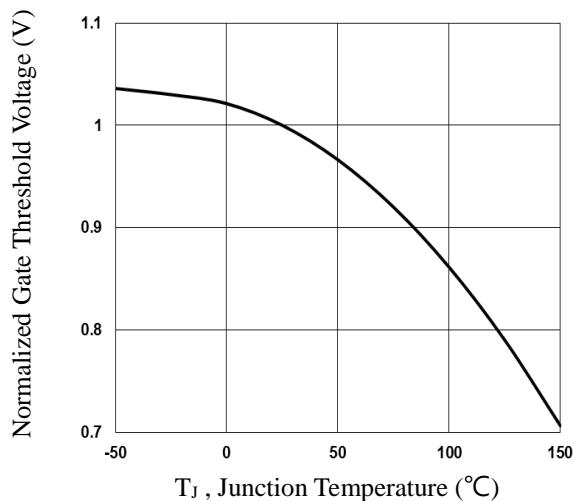


Fig.3 Normalized  $V_{th}$  vs.  $T_J$

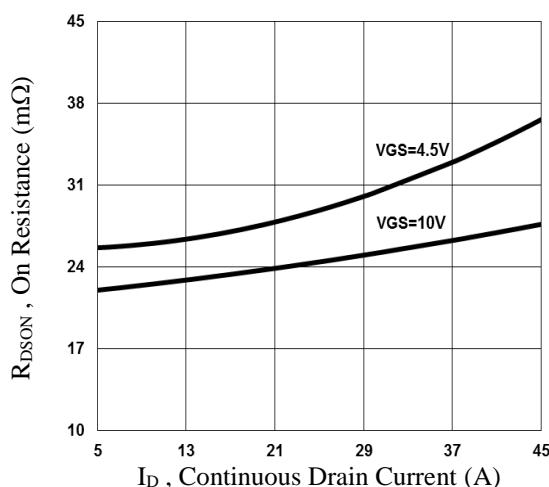


Fig.4 RDS(on) vs. Continuous Drain Current

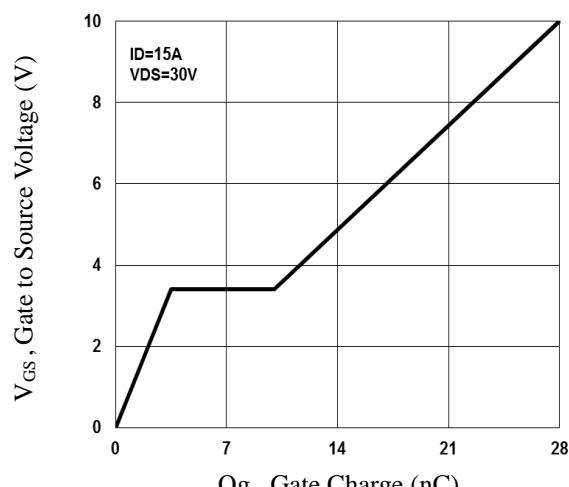


Fig.5 Gate Charge Waveform

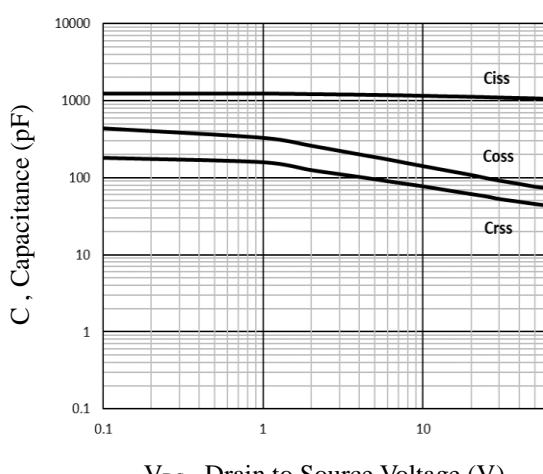


Fig.6 Capacitance Characteristics

# DEVICE CHARACTERISTICS

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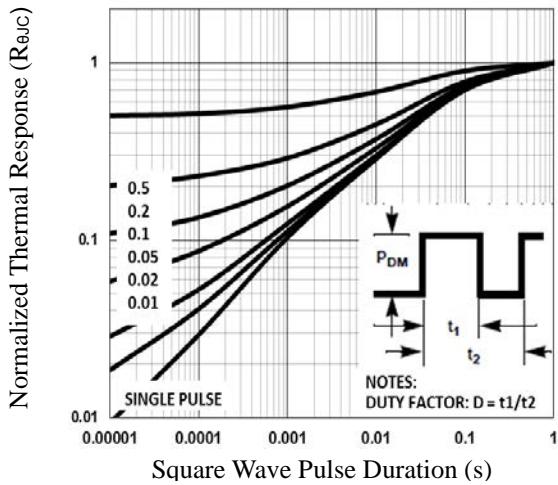


Fig.7 Normalized Transient Impedance

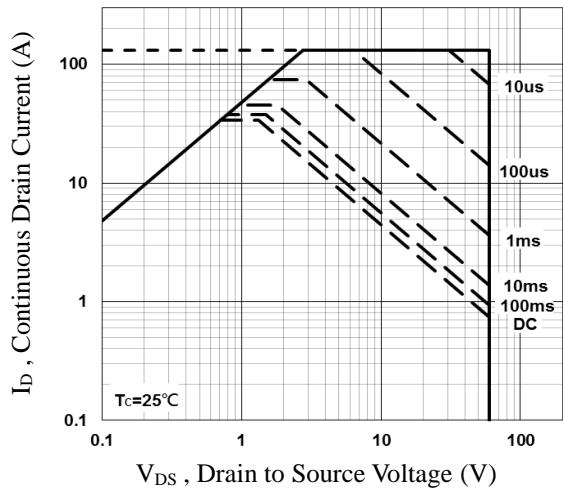


Fig.8 Maximum Safe Operation Area

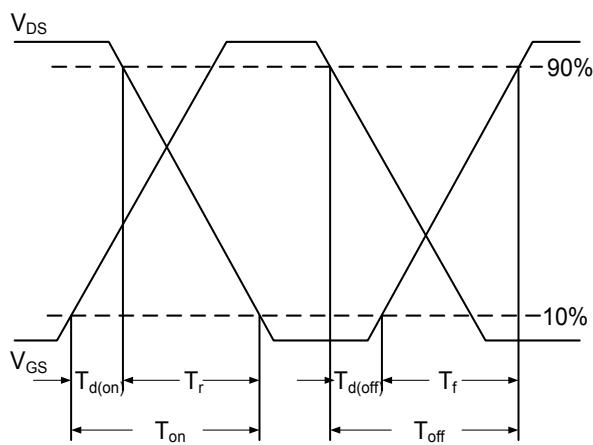


Fig.9 Switching Time Waveform

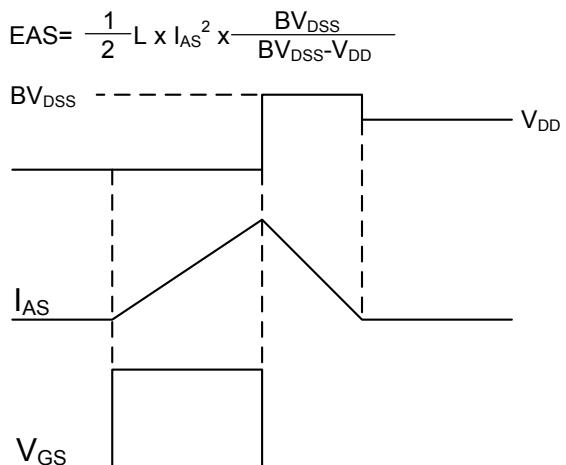
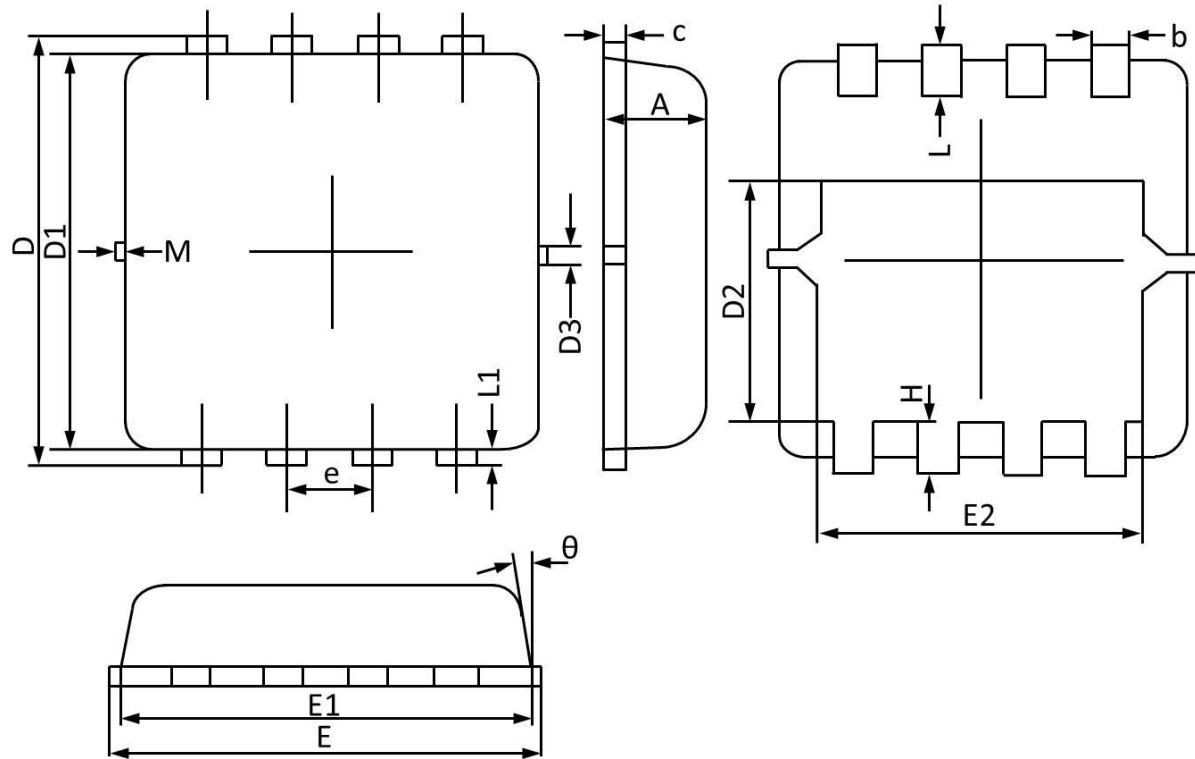


Fig.10 EAS Waveform

# PACKAGE OUTLINE & DIMENSIONS

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## PPAK3x3 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.700	0.800	0.028	0.031
b	0.250	0.350	0.010	0.013
c	0.100	0.250	0.004	0.009
D	3.250	3.450	0.128	0.135
D1	3.000	3.200	0.119	0.125
D2	1.780	1.980	0.070	0.077
D3	0.130 REF		0.005 REF	
E	3.200	3.400	0.126	0.133
E1	3.000	3.200	0.119	0.125
E2	2.390	2.590	0.094	0.102
e	0.650 BSC		0.026 BSC	
H	0.300	0.500	0.011	0.019
L	0.300	0.500	0.011	0.019
L1	0.130 REF		0.005 REF	
θ	0°	12°	0°	12°
M	0.150 REF		0.006 REF	